

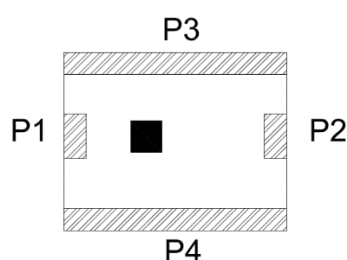
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

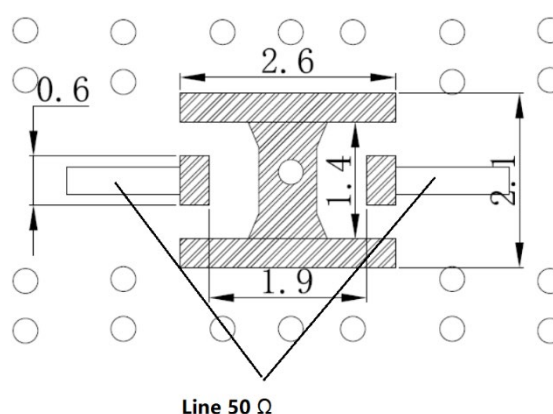
NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	5725~5850			1.2
2	VSWR				2.0
3	Ripple (dB)				1
4	Attenuation (dB)	902~928	50		
		3919~4044	30		
		4822~4947	30		
5	In/Output Impedance (Ω)			50	
6	Permissible Input Power (W)				1
Operating & Storage Condition (Component) Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C ~ +85°C					
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 °C Humidity: 30 to 70% relative humidity					

Construction



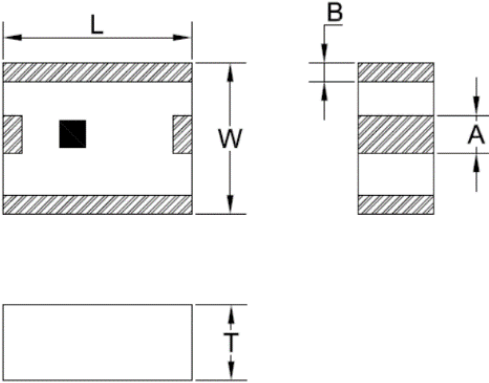
PIN	Connection	PIN	Connection
1	Input port	3	GND
2	Output port	4	GND

Mounting Considerations



Unit: mm

Dimensions

Figure	Symbol	Dimension (mm)
	L	2.50±0.20
	W	2.0±0.20
	T	1.0±0.20
	A	0.50±0.10
	B	0.20±0.10